ABSTRACT

Provided is a laminate or the like including a support substrate, a semiconductor substrate or an electronic device substrate, and an adhesive layer provided between the semiconductor substrate or the electronic device substrate and the support substrate, the laminate being capable of controlling a peeling interface when peeling a semiconductor wafer from the support substrate.

The laminate includes a support substrate, a semiconductor substrate or an electronic device substrate, and an adhesive layer provided between the semiconductor substrate or the electronic device substrate and the support substrate,

in which a primer coating film is formed on a substrate surface of any one of the semiconductor substrate, the electronic device substrate, and the support substrate, and

the primer coating film is a primer coating film formed from a composition for forming a primer coating film, the composition being for increasing adhesive strength between a substrate and an adhesive layer formed from an adhesive composition containing an adhesive component that cures by a hydrosilylation reaction and containing a component contributing to the hydrosilylation

reaction.

FIG. 1